APPLICA	BLE ST	ANDARD										
Operating temperature r			-55 °(; to 85 °(;		Storage range	ge temperature10℃		-10°C TO 50°C(Packed	C TO 50℃(Packed condition)			
RATING	Voltage	are range	30V AC / DC		Operating or stora			Re	Relative humidity 90 % MAX (Not dev			
	Current		3 0.3 A		humidity range Applicable cable			t=0.3±0.03mm, Gold plating				
	Current		SPEC	IFICA	ATION	JS						
IT	EM		TEST METHOD	11 107	11101	••	F	REQU	IREMENTS	QT	AT	
CONSTR	RUCTIO	N			L						1	
General exa	mination	Visually a	and by measuring instrumen	nt.		According to drawing.				×	×	
Marking		Confirme	Confirmed visually.			(note 1)			×	×		
		HARACTE								T	1	
Voltage prod			90 V AC for 1 min.			No flashover or breakdown.				×		
Insulation resistance			100 V DC.			50 MΩ MIN.				×	_	
Contact resis	stance	AC 20 m\	AC 20 mV MAX , 1 mA .			100 mg	Ω MAX.			×	_	
						Including FPC bulk resistance (L=8mm)						
MECHAN Vibration	IICAL C	HARACTE		lo.	Г	(1) A!	ala-t-'	، الما	amatina alba a e e e e	1 .	1	
vibration			Frequency 10 to 55 Hz, half amplitude 0.75 mm, for 10 cycles in 3 axial directions.						ontinuity of 1 μs. e: 100 mΩ MAX.	×	-	
Shock		981 m/s ²	981 m/s ² , duration of pulse 6 ms			② Contact resistance: 100 mΩ MAX.③ No damage, crack and looseness of parts.				×	-	
Mechanical operation			at 3 times in 3 both axial directions. 10 times insertions and extractions.			① Contact resistance: 100 mΩ MAX.			×	<u> </u>		
			times insertions and extractions.			(2) No damage, crack and looseness of parts.						
FPC insertio	n force		by applicable FPC	m		Insertion force : Direction of insertion				×	_	
		`	(Thickness of FPC shall be t=0.30mm at initial condition.)				2.6+0.14 × n N MAX (<i>note 2</i>) (n: Number of contacts)					
FPC retention	n force		Measured by applicable FPC			Retention force : Direction of extraction			×	_		
		`	(Thickness of FPC shall be t=0.30mm at initial condition.)				5+0.07 × n N MIN (<i>note3</i>) (n: Number of contacts)					
FNVIROI	MENT		ACTERISTICS			(n: Nur	nber of c	ontac	is)			
Corrosion sa			at 35±2 °C, 5 % salt water	r sprav		1) Cor	ntact resi	stance	e: 100 mΩ MAX.	×	T —	
		for 96 h.										
Rapid chang temperature	e of	•	Temperature-55→+15 _{TO+35} →+85→+15 _{TO+35} °C			 ① Contact resistance: 100 mΩ MAX. ② Insulation resistance: 50 MΩ MIN. 			×	_		
temperature			Time $30 \rightarrow 2 \text{ to } 3 \rightarrow 30 \rightarrow 2 \text{ to } 3 \text{ min}$ Under 5 cycles.			_			and looseness of parts			
Damp heat	.\		Exposed at 40±2 °C,							×	_	
(steady state) Damp heat,cyclic			Relative humidity 90 to 95 %, 96 h. Exposed at -10 to +65 °c,			① Cor	ntact resi	stance	e: 100 mΩ MAX.	×	 	
	,	Relative I	Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.			 ② Insulation resistance: 1 MΩ MIN. (At high humidity) ③ Insulation resistance: 50 MΩ MIN. (At dry) ④ No damage, crack and looseness of parts 						
		10 cycles										
<u>. </u>												
COUN	Т		ON OF REVISIONS		DESIGN				CHECKED	+	TE	
3 REMARK	DIS-		DIS-F-00010250		SE. YOKOYAMA				-	0713		
i t⊏i∧i\d\U\						CHECK DESIGN					0404 0404	
										+	0404	
Unless otherwise specified, refer to IEC 60512.						DRAV		HH. MURAKAMI	1	0404		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DR	DRAWING NO. ELC-368163-							
				PART NO.		140.	FH62-**S-0. 25SHW(10			•		
HS.	<u> </u>		PECIFICATION SHEET OSE ELECTRIC CO., LTD.			CODE NO.		· · · · · · · · · · · · · · · · · · ·		<u>A</u>	1/2	
FORM HDOO11			COL LLLOTTIIO CO., LTD.			CODE NO.		ULUOU A			.,_	

	SPECIFICATI	ONS		
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ
Dry heat	Exposed at 85±2°C, 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Cold	Exposed at -55±3°C, 96 h.	② No damage, crack and looseness of parts	×	_
Sulphur dioxide [JIS C 60068-2-42]	Exposed at 40 ± 2 °C, Relative humidity $80\pm5\%$ 25 ± 5 ppm for 96 h.	① Contact resistance: 100 mΩ MAX.	×	_
Hydrogen sulphide [JIS C 60068-2-43]	Exposed at 40 ± 2 °C, Relative humidity $80\pm5\%$, 10 to 15 ppm for 96 h.		×	_
Solderability	Soldered at solder temperature, 245±3°C for immersion duration,3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	_
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250 °C MAX. Reflow TMP. over 220 °C 60 to 90 sec. Number of reflow: 2 times 2) Soldering irons: TMP. 350±10 °C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (note 4)	×	_

(note 1)

This product features top-contact point.

"One Action Lock" completes FPC lock just by inserting the FPC.

Do not operate the locking-lever when inserting the FPC.

(note 2)

Do not insert the FPC to this product at an angle.

(note 3)



There's a case which FPC retention force doesn't fulfill the value, because FPC specification affects the result of FPC retention force.

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

(note 4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-368163-10-01		
HS.	SPECIFICATION SHEET	PART NO.	FH62-**S-0. 25SHW(10)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	▲	2/2